REVISION HISTORY

REVISION	DESCRIPTION	DATE	APPROVAL
A	INITAL RELEASE	JULY 15, 2016	MB
B	1. NO BOM CHANGES 2. ADD SCHEMATIC TEXT TO INDICATE ISOLATED GROUND ROUTING FOR AGND ON PARTS IN ITEM 3 3. DISCONNECTED THESE PARTS FROM GROUND PLANES C70, C72, C89, C90, C91 J3, J10, J12, J14, J15, J18 R9, R38, R43, R45, R48 4. ROUTED GND PINS FROM ABOVE DEVICES DIRECTLY BACK TO PINS 10 AND 11 OF DUT ON INNER LAYER 1 KEEPING ROUTES ISOLATED FROM GROUND PLANE.	AUGUST 23, 2016	MB

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Orderable: TPA3244EVM
TID #: N/A
Number: AAP071 Rev: B
SVN Rev: Version control disabled
Drawn By: LDN
Engineer: MATT BEARDSWORTH

Designed for: Public Release Mod. Date: 8/23/2016
Project Title: TPA3244DDW Evaluation Module
Sheet Title: REVISION HISTORY
Assembly Variant: 001 Sheet: 1 of 5
File: AAP071B_RevisionHistory.SchDoc Size: Letter
Contact: http://www.ti.com/support

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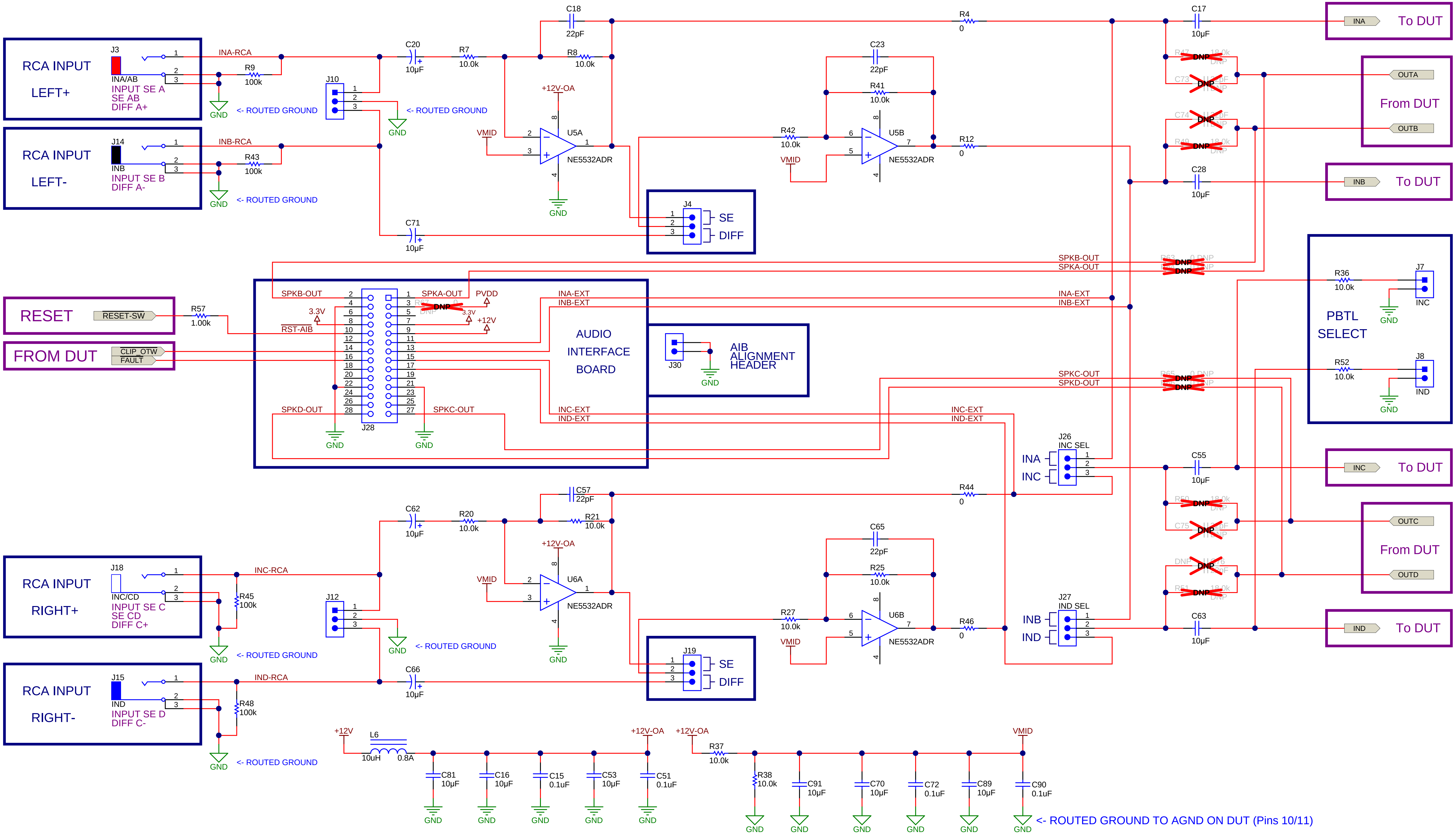

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Orderable: TPA3244EVM		Designed for: Public Release	Mod. Date: 8/22/2016
TID #: N/A		Project Title: TPA3244DDW Evaluation Module	
Number: AAP071	Rev: B	Sheet Title: Main Schematic	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 2 of 5
Drawn By: LDN		File: AAP071B_ANA-MUX.SchDoc	Size: B
Engineer: MATT BEARDSWORTH		Contact: http://www.ti.com/support	

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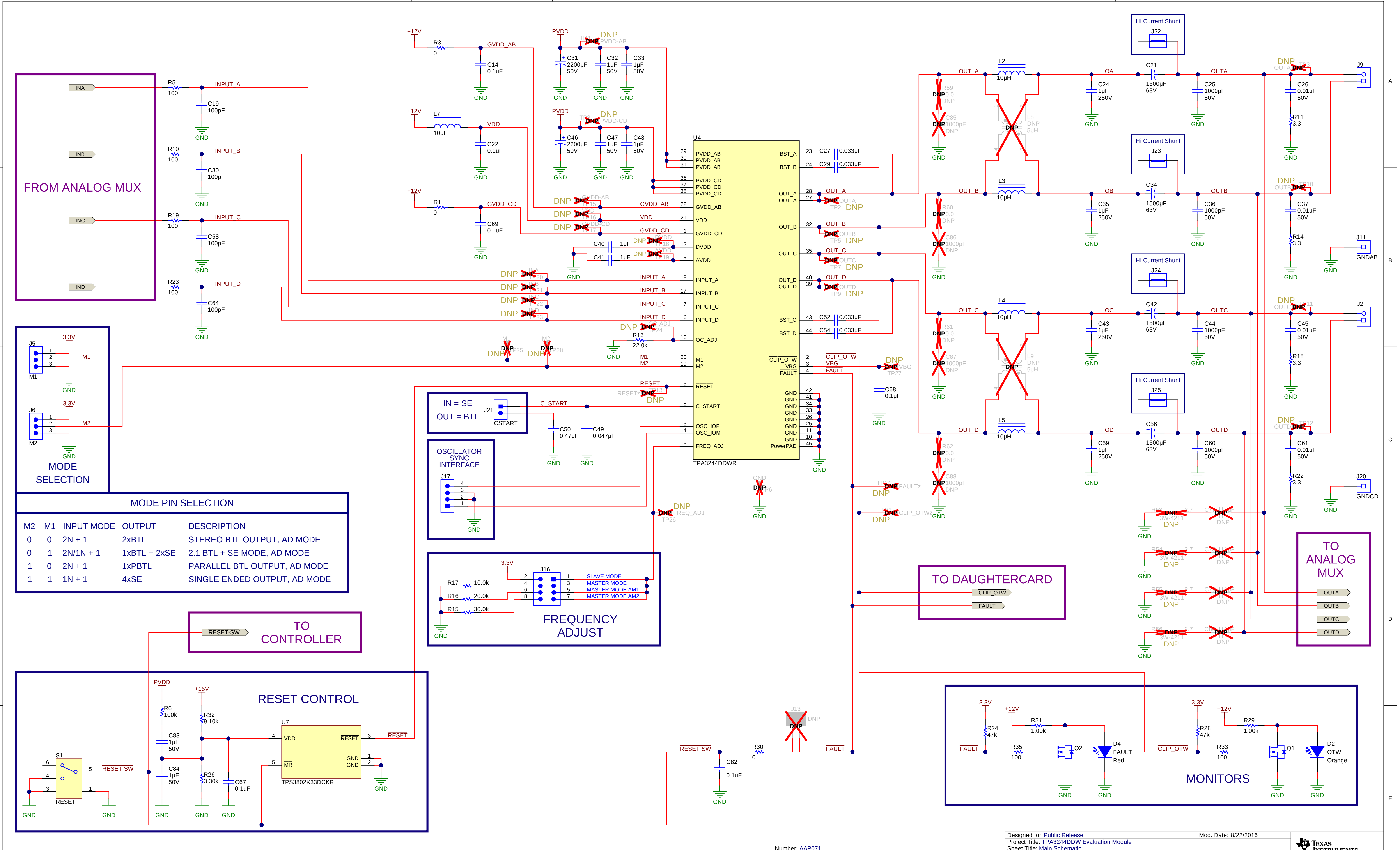

MODE PIN SELECTION

M2	M1	INPUT MODE	OUTPUT	DESCRIPTION
0	0	2N + 1	2xBTL	STEREO BTL OUTPUT, AD MODE
0	1	2N/1N + 1	1xBTL + 2xSE	2.1 BTL + SE MODE, AD MODE
1	0	2N + 1	1xPBTL	PARALLEL BTL OUTPUT, AD MODE
1	1	1N + 1	4xSE	SINGLE ENDED OUTPUT, AD MODE

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Number: AAP071	
SVN Rev: Version control disabled	
Drawn By: LDN	
Engineer: MATT BEARDSWORTH	
Designed for: Public Release	Mod. Date: 8/22/2016
Project Title: TPA3244DDW Evaluation Module	
Sheet Title: Main Schematic	
Assembly Variant: 001	Sheet: 3 of 5
File: AAP071B_TPA3244-IO.SchDoc	Size: BC Rev: B
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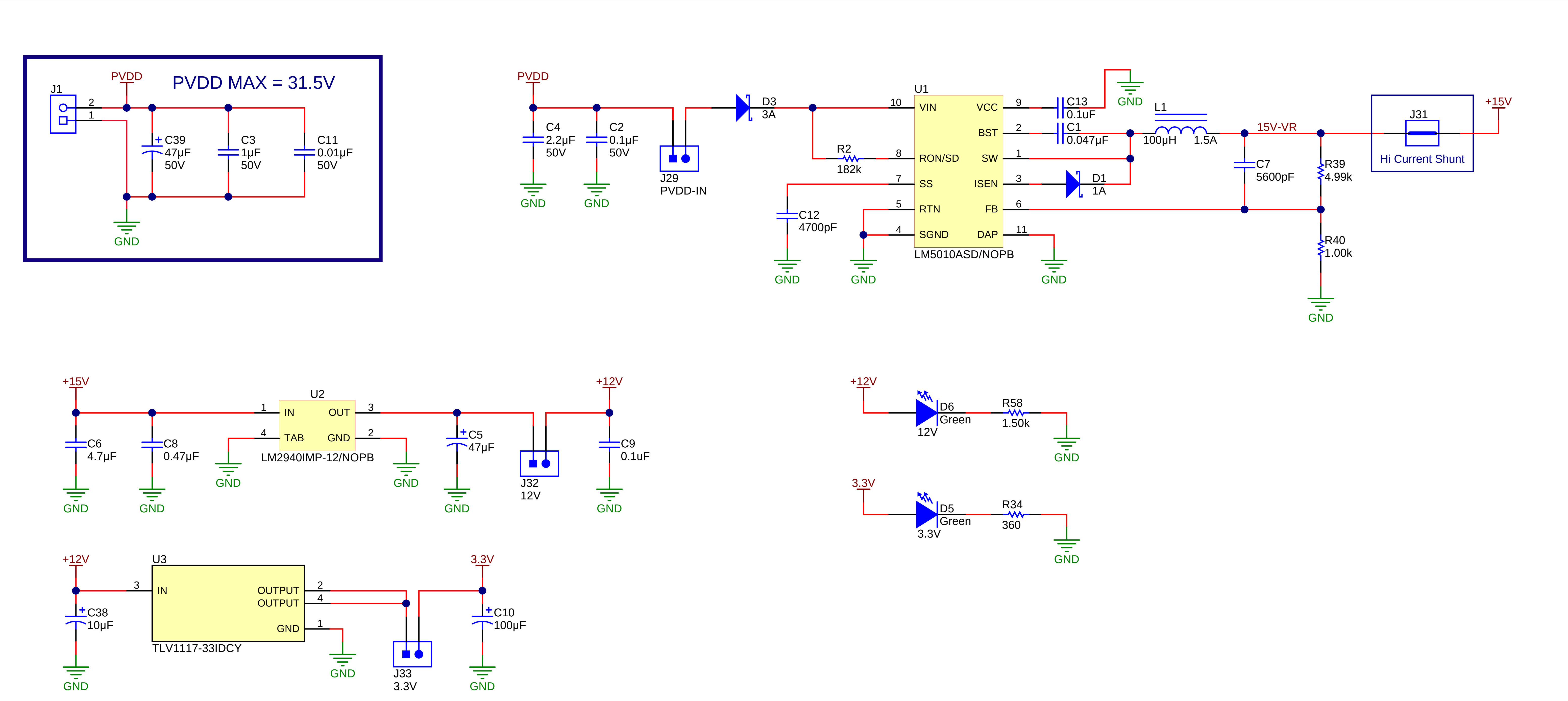

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Number: AAP071
SVN Rev: Version control disabled
Drawn By: LDN
Engineer: MATT BEARDSWORTH
Sheet: 4 of 5

Designed for: Public Release
Project Title: TPA3244DDW Evaluation Module
Sheet Title: Hardware
Assembly Variant: 001
File: AAP071B_PowerSupplies.SchDoc
Contact: http://www.ti.com/support
Mod. Date: 8/22/2016
Size: AB
Rev: B

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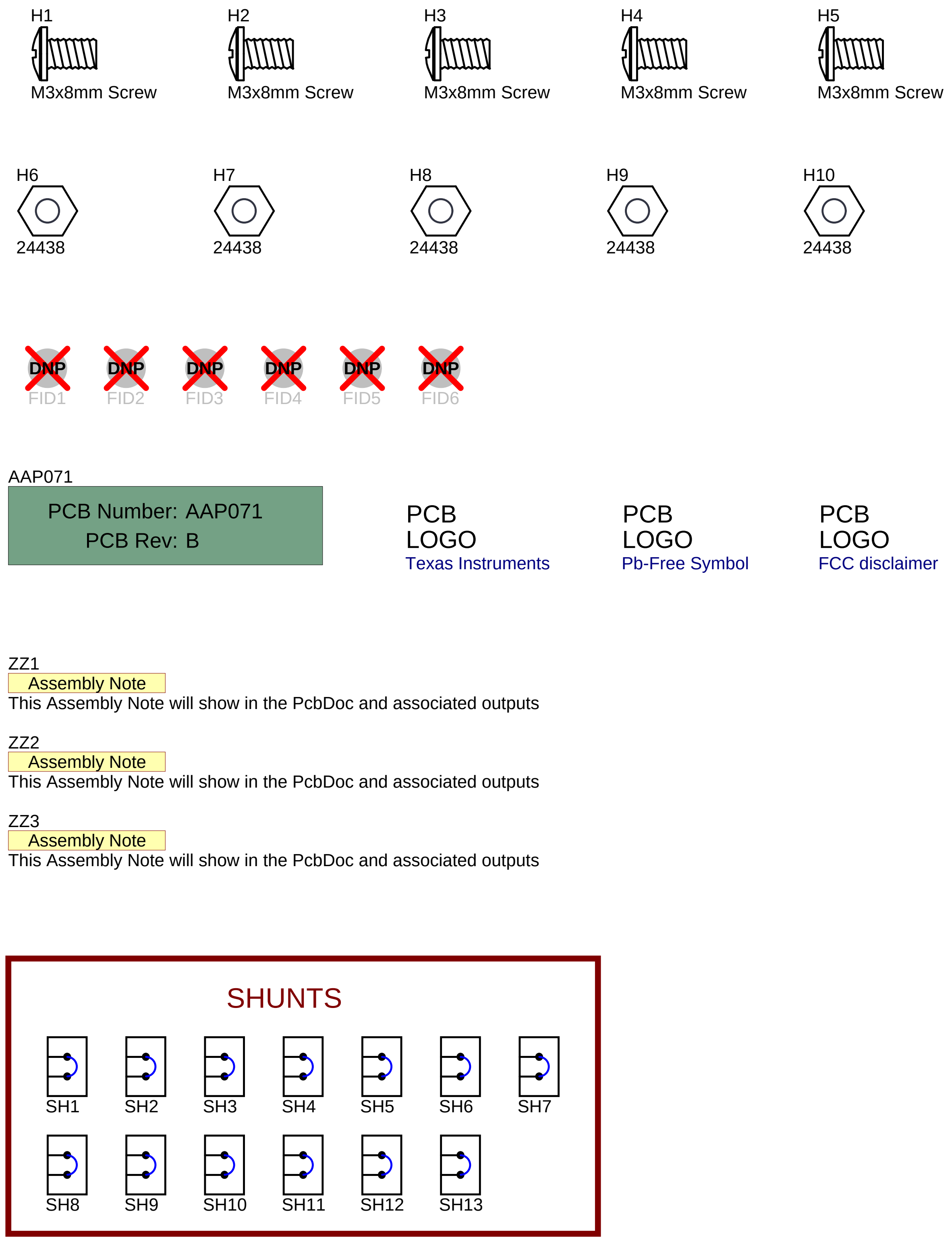

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Orderable: TPA3244EVM		Designed for: Public Release	Mod. Date: 8/22/2016
TID #: N/A		Project Title: TPA3244DDW Evaluation Module	
Number: AAP071	Rev: B	Sheet Title: Hardware	
SVN Rev: Version control disabled		Assembly Variant: 001	Sheet: 5 of 5
Drawn By: LDN		File: AAP071B_EVM_Hardware.SchDoc	Size: Letter
Engineer: MATT BEARDSWORTH		Contact: http://www.ti.com/support	

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